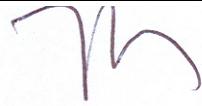




<b>Contact Date:</b>	<b>Implementation Date:</b>	<b>Alert Category:</b>	<b>Alert Type:</b>	<b>PCN #:</b>
May 23, 2008	June 21, 2008	Discrete Semiconductor	Bond Wire Change	<b>PCN #: 1111</b>
<b>TITLE</b>				
COPPER BOND WIRE IMPLEMENTATION				
<b>IMPACT</b>				
None				
<b>DESCRIPTION OF CHANGE</b>				
Improve selected electrical and mechanical properties by changing from gold to copper bond wire.				
<b>PRODUCTS AFFECTED</b>				
2N7002A-7, DMN66D0LDW-7, DMN3150L-7, DMP2130LDM-7, DMP2215L-7, DMN3033LSN-7				
<b>WEB LINKS</b>				
<b>Manufacturer's Notice:</b>	<a href="http://www.diodes.com/products/PCNs.shtml">http://www.diodes.com/products/PCNs.shtml</a>			
<b>For More Information Contact:</b>	<a href="http://www.diodes.com/contact">http://www.diodes.com/contact</a>			
<b>Data Sheet:</b>	<a href="http://www.diodes.com/index.php">http://www.diodes.com/index.php</a>			
<b>DISCLAIMER</b>				
Unless a Diodes Inc. Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				
<b>PCN APPROVAL</b>				
<b>Signatories</b>	<b>Name</b>	<b>Signature</b>	<b>Date</b>	
Signature of Sr. Vice President, Sales & Mktg.	Mark King		23 May 2008	
Signature of VP Corporate Administration	Ed Tang		23 May 2008	
Signature of VP Product Development	Francis Tang		23 May 2008	



PCN-1111\_Rev 00  
Part Number Listing

<b>Part Number</b>
2N7002A-7
DMN66D0LDW-7
DMN3150L-7
DMP2130LDM-7
DMP2215L-7
DMN3033LSN-7